

ABSTRACT OF THE DISCLOSURE

A wafer stage having a built-in heater therein mounts a heat conductive disk which mounts thereon an object wafer having an AIAs layer therein. The heat conductive disk
5 has a thermal conductivity equal to or higher than 100 watts/K/meter. The Al-oxidized area in the AIAs layer has excellent in-plane uniformity for the width thereof due to desirable heat distribution of the wafer caused by the heat conductive disk.

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